Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model
[List multiple models if applicable.]

HP 2309p Flat Panel Monitor
Name / Model #2
Name / Model #3
Name / Model #4
Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>3</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>4</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>3</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#2</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Stand Rear Upper Cover From Stand Base
2. Take Screw(*2) From Stand BKT & Remove Stand Base Form Display Head
3. Remove Front Cover From Display Head
4. Remove Rear Cover Ass’y From Display Head
5. Remove Sub Bezel Ass’y From Rear Cover
6. Remove Sub Bezel From Trim Ring
7. Remove Function Key Board From Trim Ring
8. Remove Kingston Lock BKT From Rear Cover
9. Take Screw(*4) Off From Chassis Cover & Remove Panel
10. Take Screw(x6) Off From Power Bd & Interface Bd & Invter Bd & Remove Chassis Cover
11. Remove Mylar From Chassis Cover
12. Take Screw(*4) Off From VESA Mount
13. Remove VESA Cover From VESA Mount BKT
14. Take Screw(*2) Off From Vesa Plug
15. Take Screw(*1) Off From Stand Base BKT
16. Take Screw(*2) Off From Stand Base BKT
17. Take Screw(*4) Off From Base BKT
18. Remove Stand Rear Lower Cover From Stand Base BKT
19. Take Screw(*4) Off From Stand Base BKT
20. Remove Base Rubber(*5) From Base BKT
21. Take Screw(*2) Off From Base Trim Cover
22. Take Screw(*4) Off From Base BKT

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
HP-2309P Disassembly Process

- April Chiu
- Mechanical Engineer
- Feb-27-2009
External Electric Cables Dissecting Process

1. Remove Cable From Display Head.

2. Dissecting To Complete.
Remove Stand Rear Upper Cover From Stand Base

2. Dissecting To Complete.
Take Screw(*2) From Stand BKT & Remove Stand Base Form Display Head

1. Take Screw(*2) From Stand BKT & Remove Stand Base Form Display Head

2. Dissecting To Complete.
Remove Front Cover From Display Head


2. Dissecting To Complete.
Remove Rear Cover Ass’y From Display Head
1. Remove Sub Bezel Ass’’y From Rear Cover.

2. Remove Rubber From Sub Bezel Ass’’y.
Remove Sub Bezel From Trim Ring

1. Remove Sub Bezel From Trim Ring.

2. Dissecting To Complete.
Remove Function Key Board From Trim Ring

1. Use tool, let the rubber melt, and remove Lens & Function Key.
Remove Kingston Lock BKT From Rear Cover

1. Use tool, let the rubber melt, and remove Kingston Lock BKT.
Take Screw(*4) Off From Chassis Cover & Remove Panel

1. Remove connector from Chassis cover.
2. Take Screw(x4) Off from Chassis cover & Remove Speaker Off From Chassis Cover.
3. Remove connector off from Panel.
4. Remove the panel.
Take Screw(x6) Off From Power Bd & Interface Bd & Invter Bd & Remove Chassis Cover (Printed Circuit Assemblies>10cm**2)

1. Take screw(*6) off from PCB.

2. Take screw(*6) off from P.C.B.

3. Remove Connector off from P.C.B.
Take Screw(x6) Off From Power Bd & Interface Bd & Invter Bd & Remove Chassis Cover (Printed Circuit Assemblies>10cm**2)

Dissecting to complete.
Remove Mylar From Chassis Cover
LCD PANEL EXPLODE

Step 1: Rear side view

Step 2: Unfix the screws (3 Points)

Step 3: Remove the Cover Shield

Step 4: Separate wires from the tape
Step 5: Dismantle the case top (Down)

Step 6: Dismantle the case top (left/right)

Step 7: Separate case top (push the case top because of damages on COF)

Step 8: Separate Board Assy
LCD PANEL EXPLODE

Step 9: Unfix the BL Screw

Step 10: Remove S/Main

Step 11: Remove the Optical Sheets

Step 12: Remove the LGP
LCD PANEL EXPLODE

Step 13: remove lamp wire tapes (left/right)

Step 14: Separate wires from Cover bottom

Step 15: Separate Lamp holder(H) from holder Guide of Cover bottom

Step 16: Separate Lamp holder(G) from holder Guide of Cover bottom.
Final : Lamp Assy
**Electrolytic Capacitors Over 25mm High & Diameter Dissecting Process**

1. Heats Up, Dissolved Tin Lead.
2. Takes Down The Capacitor.
3. Dissecting To Complete. (Next Page Have Description)
Electrolytic Capacitors Process Drawing
Take Screw(*4) Off From VESA Mount

1. Take screw(*4) off from VESA Mount.
2. Remove VESA Mount From Stand Base.
Remove VESA Cover From VESA Mount BKT

1. Use a tool, let the rubber melt, and remove the VESA cover.
1. Take screw(*2) off from Vesa Plug.
2. Remove Vesa Plug Cover From Stand Base.
1. Take Screw(*1) Off From Stand Base BKT

2. Remove Slide Cover From Stand Base.
1. Take screw(*2) off from Stand Base BKT.

2. Both Hands Downwardly.

3. Remove Stand Front Upper Cover From Stand Base.
Take Screw(*4) Off From Base BKT

1. Take screw(*4) off from Base BKT.
2. Dissecting To Complete.
Remove Stand Rear Lower Cover From Stand Base BKT
Take Screw(*4) Off From Stand Base BKT

1. Take screw(*4) off from Stand Base BKT.

2. Downwardly To Rotate.

3. Remove Stand Front Lower Cover from Stand Base BKT.

4. Dissecting To Complete.
Remove Base Rubber(*5) From Base BKT
Take Screw(*2) Off From Base Trim Cover

2. Dissecting To Complete.
Take Screw(*4) Off From Base BKT

1. Take Screw(*4) Off From Base BKT

2. Dissecting To Complete.